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Applicants: Atsushi YABE et al

For: ELECTROLESS COPPER PLATING SOLUTION AND

ELECTROLESS COPPER PLATING METHOD

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Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

INFORMATION DISCLOSURE STATEMENT

Sir:

In compliance with the provisions of Rules 1.97(e)(1) and 1.98, enclosed herewith is a copy of the European Patent Office Search Report, Form PTO-1449 and the references cited thereon. The relevance of these references is explained on the enclosed search report. Accordingly, further comment at this point in time should not be necessary.

I hereby certify that each item of information contained in this Information Disclosure Statement was cited in a communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of this statement.

Further consideration is respectfully solicited.

Respectfully submitted,

TFC/smd

Terryence F. Chapman

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Encl: Copy of European Patent Office Search Report dated June 12, 2008 (3 pages)
Form PTO-1449 and references cited thereon Postal Card

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on August 5, 2008.

Terryente F. Chapman

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